Docket No.:			
<u>DECLARAT</u>	TION AND POWER C	<u>OF ATTORNEY</u>	
As a below named inventor, I hereby	declare that:		
My residence, post office and citizens	ship are as stated below next to my n	name,	
inventor (if plural names are listed l	below) of the subject matter claime	listed below) or an original, first and joint and for which a patent is sought on the the specification of which	
[x] is attached hereto [] was f	iled on as App	lication Serial No and was	
amended on	(if applicable	:)	
I hereby state that I have reviewed a claims, as amended by any amendme		above identified specification, including the	
I acknowledge the duty to disclose in with Title 37, Code of Federal Regula		o be material to patentability in accordance	
or inventor's certificate, or 365(a) of than the United States of America, lis	any PCT international application wh sted below and have also identified be ertificate, or of any PCT internations	(b) of any foreign application(s) for patent hich designated at least one country other below, by checking the box, any foreign al application having a filing date before	
Prior Foreign Application(s): Number	<u>Country</u>	Foreign Filing Date Month/Day/Year	
74387/2003	Korea	10/23/2003	
I hereby claim the benefit under 35 U	J.S.C. 119(e) of any United States pr	rovisional application(s) listed below.	
Application Number(s):	<u>Filing Date (</u>	Filing Date (Month/Day/Year)	
international application designating each of the claims of this application the manner provided by the first par	the United States of America, listed is not disclosed in the prior United ragraph of 35 U.S.C. 112, I acknowled in 37 CFR 1.56 which became as	ates application(s), or 365(c) of any PCT I below and, insofar as the subject matter of d States or PCT international application in edge the duty to disclose information which vailable between the filing date of the prior cation.	
Prior U. S. Application or PCT Parent Number PCT/KR2004/002377	Filing Date (Month/Day/Year) September 16, 2004	Parent Patent Number (if applicable)	
101/102004/0023//			

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the following attorney(s) and/or agent(s) associated with Customer Number 34610 with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith. <u>Direct all correspondence to Customer Number 34610</u>.

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